

## ABSTRACT

A semiconductor device includes a semiconductor chip having a main surface provided with an integrated circuit including a photoelectric  
5 converter and a first wiring for electrically connecting the integrated circuit  
of the semiconductor chip to respective external terminals. The  
semiconductor device also includes a sealing resin for sealing the main  
surface of the semiconductor chip and the first wiring, formed so as to have  
an opening over the surface of the integrated circuit and a light-transmitting  
10 cap for covering the opening of the sealing resin.